Brevin Tilmon

Email Personal Website Github

I am a PhD student skilled in computational photography, computer vision, and machine learning.

Education

Ph.D. Electrical Engineering

2019-Present

University of Florida Advisor: Dr. Sanjeev Koppal

B.S. Engineering Physics

2015-2019

Murray State University, 3.8/4.0

Publications Available at Personal Website

- 1. Brevin Tilmon, Eakta Jain, Silvia Ferrari, Sanjeev Koppal. "FoveaCam: A MEMS Mirror-Enabled Foveating Camera". International Conference on Computational Photography 2020.
- 2. Francesco Pittaluga, Zaid Tasneem, Justin Folden, Brevin Tilmon, Ayan Chakrabarti, Sanjeev Koppal. "A MEMS-Based Foveating LIDAR to Enable Real-Time Adaptive Depth Sensing". arxiv 2020.
- Kristofer Henderson, Xiaomeng Liu, Justin Folden, Brevin Tilmon, Suren Jayasuriya, Sanjeev Koppal. "Design and Calibration of a Fast Flying-Dot Projector for Dynamic Light Transport Acquisition". Transactions on Computational Imaging 2020.
- 4. Gheorge Bunget, Brevin Tilmon, Andrew Yee, Dylan Stewart, James Rogers, et al. "Novel Approach of Wavelet Analysis for Nonlinear Ultrasonic Measurements and Fatigue Assessment of Jet Engine Components". American Institute of Physics 2018.

Experience

Graduate Research Assistant

2019-Present

Florida Optics and Computational Sensor Lab, University of Florida

Develop adaptive computational cameras leveraging computational photography, computer vision, machine learning and optics.

Undergraduate Research Assistant

2016-2019

NDE Lab, Murray State University and FOCUS Lab, University of Florida

Electrical Engineering Intern

2017

Berry Global Inc.

IEEE Robotics Club President

2017-2019

Murray State University

Awards

NSF GRFP Honorable Mention	2020
Graduate School Preeminence Award, University of Florida	2019-2024
Kirkland Fellowship, University of Florida	2019-2021
Jesse & Deborah Jones Scholarship, Murray State University	2015-2019
Housing Scholarship, Murray State University	2015-2018

Skills

Programming: C/C++, Python, MATLAB

Sensors and Robotics: Machine vision cameras, depth sensors, MEMS Devices, Micro-controllers